

PRODUCTION OF LAMINATES FOR PRINTED WIRING BOARDS USING PROTECTIVE CARRIER

Abstract of the Disclosure

A laminate to be used in the manufacture of printed circuit boards is formed by contacting one surface of a layer of a conductive foil (*e.g.*, copper foil) with protective-carrier sheeting (*e.g.*, aluminum foil) and the other surface of the conductive foil with a dielectric layer (*e.g.*, prepreg). The contacted layers are stacked and cut to desired dimensions. The process is performed without use of adhesive or mechanical attachment. Consequently, contamination and the occurrence of imperfections in the conductive foil of a laminate to be used in a printed wiring board can be substantially reduced.

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